

TPS587/588/589

Two-Part Thermally Conductive Gap Filler

LiPOLY's TPS range are two-part silicone-based, cure in place, thermally conductive gap fillers which can be used to couple hot electronic components on PC boards with an adjacent metal case or heat-sink.



Features-

- Thermal conductivity: 0.8/1.5/2.0 W/m*K
- Two-part liquid gap filler
- Fast cure time

Typical Applications-

- Automotive electronics
- Telecommunications
- Computer and peripherals
- Thermally conductive vibration dampening
- Between any heat-generating component and a heat sink

Shelf Life-

- 12 months unopened under standard conditions

Typical Properties-

PROPERTY	TPS587	TPS588	TPS589	TEST METHOD	UNIT
Color	White/Gray	White/Gray	White/Gray	-	-
Resin Base	Silicone	Silicone	Silicone	-	-
A:B	1:1	1:1	100:3	-	-
Viscosity (dynamic at 23")	15	20	5	ASTM D2196	PaS
Density	2.15	2.0	1.8	ASTM D792	g/cm ³
Application temperature	-60~180	-60~180	-60~180	-	°C
Curing Condition 1	100°C/5 min	100°C/5 min	RT 7 day	-	-
Curing Condition 2	60°C/30 min	60°C/30 min	-	-	-
Curing Condition 3	25°C/300 min	25°C/300 min	-	-	-
Hardness	10	25	50	ASTM D2240	Shore A
ELECTRICAL					
Dielectric breakdown	350	350	350	ASTM D149	V/mil
Volume resistivity	>10 ¹³	>10 ¹²	>10 ¹¹	ASTM D257	Ohm-m
THERMAL					
Thermal Conductivity	2.0	1.5	0.8	ASTM D5470	W/m*K